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(54) Title (EN): SUBSTRATE DEVICE AND METHOD FOR PRODUCING SUBSTRATE DEVICE

(54) Title (FR): DISPOSITIF DE SUBSTRAT ET PROCÉDÉ DE PRODUCTION DE DISPOSITIF DE SUBSTRAT

(54) Title (JA): 基板装置、および基板装置の製造方法

(57) Abstract:

(EN): The present disclosure pertains to a substrate device and a method for producing the substrate device, capable of improving reliability and the produced quality of the substrate device as electronic hardware. According to the present invention, a plurality of sheet-like substrates in which wiring patterns are formed are stacked on one another to form a single-piece substrate having internal wiring, whereby two substrates are connected both physically and electrically. The disclosure is applicable to a substrate device.

(FR): La présente invention concerne un dispositif de substrat et un procédé de production du dispositif de substrat, permettant d'améliorer la fiabilité et la qualité produite du dispositif de substrat tel qu'un matériel électronique. Selon la présente invention, une pluralité de substrats stratiformes dans lesquels sont formés des motifs de câblage sont empilés l'un sur l'autre pour former un substrat monobloc comportant un câblage interne, moyennant quoi deux substrats sont reliés physiquement et connectés électriquement. L'invention est applicable à un dispositif de substrat.

(JA): 本開示は、基板装置の電子機器としての製造品質と、信頼性を向上できるようにする基板装置、および基板装置の製造方法に関する。配線パターンが形成されている複数のシート状の基板を積層することで、内部配線が形成された個片基板を形成し、個片基板により2枚の基板を物理的、かつ、電氣的に接続する。本開示は、基板装置に適用することができる。

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